PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Toshiyuki OGATA, et al.

Appln. No.: NOT YET ASSIGNED

Confirmation No.: NOT YET ASSIGNED Group Art Unit: NOT YET ASSIGNED

Filed: August 07, 2001 Examiner: NOT YET ASSIGNED

For: POSITIVE RESIST COMPOSITION AND BASE MATERIAL CARRYING LAYER OF THE POSITIVE RESIST COMPOSITION

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

10. A base material comprising:

an organic polymer layer as a first layer formed on a substrate; and

a second resist layer formed on said organic polymer layer, said second resist layer being composed of a positive resist composition according to claim 1 and having a thickness of from 50 to 200 nm.

AMENDMENT
Attorney Docket No. Q65755

REMARKS

Entry and consideration of this Amendment is respectfully requested.

Respectfully submitted,

Robert J. Seas, Jr.
Registration No. 21,092

SUGHRUE, MION, ZINN,
MACPEAK & SEAS, PLLC
2100 Pennsylvania Avenue, N.W.
Washington, D.C. 20037-3213
Telephone: (202) 293-7060
Facsimile: (202) 293-7860
RJS/ob

Date: August 7, 2001

AMENDMENT
Attorney Docket No. Q65755

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

10. A base material comprising:

an organic polymer layer as a first layer formed on a substrate; and

a second resist layer formed on said organic polymer layer, said second resist layer being composed of a positive resist composition according to ~~any one of claims 1 to 9~~ claim 1 and having a thickness of from 50 to 200 nm.